

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	118	(hysol near1 ("4323" "4451" "4450"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:11
L2	0	1 same (shrink\$4 expand\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:59
L3	10	1 and (shrink\$4 expand\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:18
L4	20	1 with cure\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:04
L5	0	1 and ((cure cured curing) with (shrink\$4 expand\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:09
L6	518	epox\$3 with ((cure cured curing) with (shrink\$4 expand\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:26
L7	504	(epoxy epoxies) with ((cure cured curing) with (shrink\$4 expand\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:26
L8	340	((epoxy epoxies) near1 resin) with ((cure cured curing) with (shrink\$4 expand\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:12

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L9	0	7 and ((hysol dexter) with ("4323" "4451" "4450"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:11
L10	175	8 and adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:14
L11	13	10 and (semiconductor chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:14
L12	20	1 and (shrink\$4 expand\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:18
L13	0	(epoxy epoxies) with ((cure cured curing) with shrink\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:27
L14	1	(epoxy epoxies) same (cure cured curing) same shrink\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 16:27